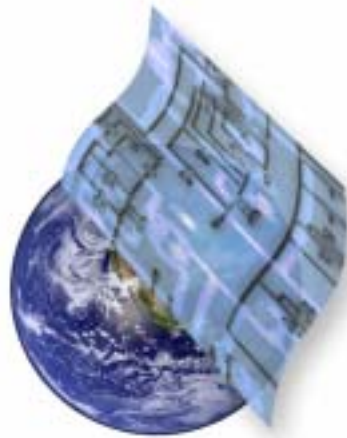


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About Printed Electronics.

The market for organic and printable electronics is expected to reach \$300BN in 2025 – larger than the size of the silicon industry today. The future electronic fabrication plants will be printing processes. Enormous markets will be created where conventional silicon chips cannot go today because they are too brittle. A full range of electrical and electronic components will be printed – from transistor circuits to displays, power and even speakers.

Uniquely, Printed Electronics World will also cover the Global Picture;

- The application of the emerging printed electronics toolkit
- progress in displays, thin film transistor circuits, sensors, power and sound
- global developments from companies around the world
- materials and manufacturing techniques
- Investing in printed/organic electronics

Who Attends

**Over 600 companies have benefited from our Printed Electronics events.
See back page for details**

Europe 2005 attracted over 180 delegates from over 20 countries including;

USA, UK, Sweden, Japan, Belgium, Germany, France, Finland, Austria, Netherlands, Ireland, Italy, Israel, Taiwan, Denmark, Singapore, Canada, Korea, Greece, Russia

Type of Delegate

- End Users
- CPG's
- Packaging Developers
- Brand Managers
- Product Designers
- Graphic Designers
- Electronics Architects
- Technology Developers
- Print Technology Developers
- Materials Developers
- Label Makers

Job titles:

Chairman, CEO, CIO, CTO, President, Managing Director, General Manager, Vice President, Director, Head of Operations, head of Development, Product/brand Director



Exhibition and Speaking Opportunities

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19-21 April, Cambridge UK

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Previous delegates have included;

3M, Acheson Industries (Europe) Ltd, Advanced Research Laboratory, Hitachi, Ltd., Agfa-Gevaert NV, Air Products & Chemicals, Inc., ALPS Electric North America, American Dye Source, Inc., Appleton Coated, Applied Materials, ARC/Newco, Arccure Technologies GmbH, Areva FCI, Argent International, ArjoWiggins R&D, Artificial Muscle, Inc., Asahi-KASEI, Ashland, ASK, Aspocomp, Assa Abloy ITG, AT&S, Avantone Oy, Avery Dennison, Aveso Printed Electronic Displays, AVT, BAE Systems, BASF Future Business GmbH, Bayer Films Americas, BE Semiconductor Industries, Boeing, Bourns Inc, Bowater Inc., Brady Corporation, Brother International Corporation, Bundesdruckerei GmbH, C G Lazarakis SA, Cabot Corporation, Cambridge Display Technology, Cambrios Technologies, Canon, Caraustar Custom Packaging Group, Carvajal S.A., Cascades Folding Cartons, CEA, Cedinsa SA, Cenamps, Centre Microélectronique de Provence, Cerbo Group, Chemnitz University of Technology, Ciba Specialty Chemicals Inc, Cima NanoTech, Cintelliq Ltd, Coates Screen, Coding Products, Columbia University, Conductive Inkjet Technology, CIT, Cookson Electronics, Coors Brewing Company, Corning, Corus Research Development & Technology, COVEME SPA, CSAT America LLC, Cummins Allison, Cymbet Corporation, Cypak AB, Dai Nippon Printing Co., Ltd., Data2, De La Rue Group , Degussa AG, DEK Printing Machines Ltd, Diageo, Dimatix, Inc, DMATEK, Dow Corning Corporation, DuPont, Ecole des Mines, Electrox Corp, Elementis Specialties, elumin8 Systems, EMD Chemicals, Emerson & Cuming, Emphasis Materials Inc, ENEA, Episys, Epson, ERSO/ITRI, ETRI, Fotango, Fraunhofer Inst, FrontCoat Technologies, General Mills, Georgia Institute of Technology, Giesecke & Devrient , Givaudan, GlaxoSmithKline, Glud & Marstrand, GPV, Graphic Controls, Graphic Solutions , Group InfoTech, Gyricon, H C Starck, Hallmark Cards, Hammer Lithograph, Harris Corporation, Hewlett Packard, Honeywell, IBM, ICI, IIC Industrial Investment Council, IM3D Limited, Imperial College, Infineon Technologies, InkTec Co., International Paper, IRF, IT Strategies, Item IQ, ITN Energy Systems, ITW Tech Center, J2 Technology Consulting, Johnson & Johnson, KCL, KDDI R&D Laboratories, Kester, Kimberly-Clark, KIMM, Kodak, Kontogeorgis Packaging, Korea Institute of Machinery and Materials, Kovio, Kraft Foods , KSG Leiterplatten, Label Design., LANXESS, Leo Paper Group, Leonhard Kurz, LG Chem, LS Industrial Systems, MacDermid, MacDonald and Evans, MAN Roland ,Max Daetwyler, MDC Max Daetwyler, MeadWestvaco, Menlo Worldwide, Merck Chemicals, Meyers, Microdrop Technologies GmbH, Ministry of Defence, Mitsubishi, Motorola, M-Real Corporation, MRL/ITRI, Technologies AG, Nanosolar., Nanotechnologies., NASA - 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